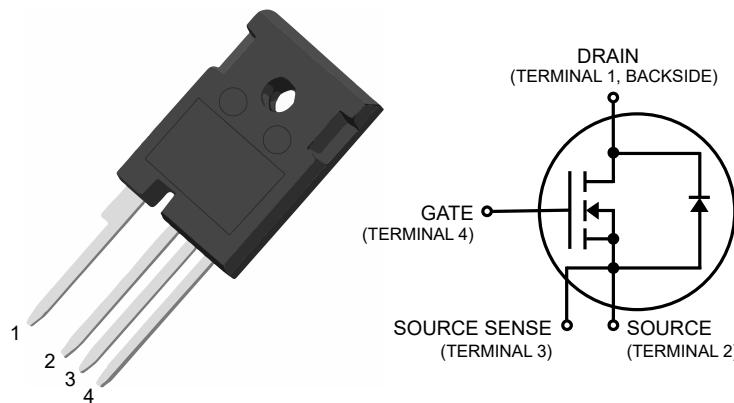


## Product Overview

700V, 15 mΩ typical at  $V_{GS} = 20V$ , 17 mΩ typical at  $V_{GS} = 18V$ , Silicon Carbide (SiC) N-Channel MOSFET, TO-247 notched 4-lead with a source sense.



## Features

- AEC-Q101 qualified option available
- Low capacitances and low gate charge
- Fast switching speed due to low internal gate resistance (ESR)
- Stable operation at high junction temperature,  $T_{J(max)} = 175\text{ °C}$
- Fast and reliable body diode
- Superior avalanche ruggedness
- RoHS compliant

## Benefits

- High efficiency to enable lighter and more compact system
- Simple to drive and easy to parallel
- Improved thermal capabilities and lower switching losses
- Eliminates the need for external freewheeling diode
- Lower system cost of ownership

## Applications

- Photovoltaic (PV) inverter, converter, and industrial motor drives
- Smart grid transmission and distribution
- Induction heating and welding
- Hybrid Electric Vehicle (HEV) powertrain and Electric Vehicle (EV) charger
- Power supply and distribution

## 1. Device Specifications

This section shows the specifications of this device.

### 1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of this device.

**Table 1-1.** Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain source voltage	700	V
$I_D$	Continuous drain current at $T_C = 25^\circ\text{C}$	112	A
	Continuous drain current at $T_C = 100^\circ\text{C}$	94	
$I_{DM}$	Pulsed drain current <sup>1</sup>	450	
$V_{GS}$	Gate-source voltage	23 to -10	V
	Transient gate-source voltage	25 to -12	
$P_D$	Total power dissipation at $T_C = 25^\circ\text{C}$	524	W
	Linear derating factor	3.4	W/ $^\circ\text{C}$

**Note:**

1. Repetitive rating: pulse width and case temperature are limited by the maximum junction temperature.

The following table shows the thermal and mechanical characteristics of this device.

**Table 1-2.** Thermal and Mechanical Characteristics

Symbol	Characteristic/Test Conditions	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction-to-case thermal resistance	—	0.22	0.29	$^\circ\text{C}/\text{W}$
$T_J$	Operating junction temperature	-55	—	175	$^\circ\text{C}$
$T_{STG}$	Storage temperature	-55	—	175	
$T_L$	Lead temperature for 10 seconds	—	—	300	$^\circ\text{C}$
—	Mounting torque, M3 screw	—	0.8	—	$\text{N}\cdot\text{m}$
Wt	Package weight	—	6.2	—	g

ESD practices should comply with JESD-625.

### 1.2 Electrical Performance

The following table shows the static characteristics of this device.  $T_J = 25^\circ\text{C}$  unless otherwise specified.

**Table 1-3.** Static Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{V}$ , $I_D = 100\text{\textmu A}$	700	—	—	V
$R_{DS(on)}$	Drain-source on resistance <sup>1</sup>	$V_{GS} = 20\text{V}$ , $I_D = 40\text{A}$	—	15	19	$\text{m}\Omega$
		$V_{GS} = 18\text{V}$ , $I_D = 40\text{A}$	—	17	—	
$V_{GS(th)}$	Gate-source threshold voltage	$V_{GS} = V_{DS}$ , $I_D = 4\text{ mA}$	1.9	3.0	5.0	V
$I_{DSS}$	Zero gate voltage drain current	$V_{DS} = 700\text{V}$ , $V_{GS} = 0\text{V}$	—	0.3	35	$\text{\textmu A}$
		$V_{DS} = 700\text{V}$ , $V_{GS} = 0\text{V}$ , $T_J = 175^\circ\text{C}$	—	3.5	—	
$I_{GSS}$	Gate-source leakage current	$V_{GS} = 20\text{V}/-10\text{V}$	—	—	$\pm 100$	nA

**Note:**

1. Pulse test: pulse width < 380  $\mu$ s, duty cycle < 2%.

The following table shows the dynamic characteristics of this device.  $T_J = 25^\circ\text{C}$  unless otherwise specified. The dynamic characteristics are characterized, not 100% tested, at the recommended operating  $V_{GS} = 20\text{V}/-5\text{V}$ .

**Table 1-4.** Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{GS} = 0\text{V}$ $V_{DD} = 700\text{V}$ $V_{AC} = 25\text{ mV}$ $f = 200\text{ kHz}$	—	4324	—	pF
$C_{rss}$	Reverse transfer capacitance		—	44	—	
$C_{oss}$	Output capacitance		—	506	—	
$Q_G$	Total gate charge	$V_{GS} = -5\text{V}/20\text{V}$ $V_{DD} = 470\text{V}$ $I_D = 40\text{A}$	—	215	—	nC
$Q_{GS}$	Gate-source charge		—	58	—	
$Q_{GD}$	Gate-drain charge		—	35	—	
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 470\text{V}$ $V_{GS} = -5\text{V}/20\text{V}$ $I_D = 50\text{A}$	—	27	—	ns
$t_r$	Voltage rise time		—	22	—	
$t_{d(off)}$	Turn-off delay time		—	40	—	
$t_f$	Voltage fall time	$R_{G(ext)} = 4\Omega$ Freewheeling diode = MSC015SMA070B4N ( $V_{GS} = -5\text{V}$ ); reference <a href="#">Figure 1-18</a>	—	12	—	$\mu\text{J}$
$E_{on}$	Turn-on switching energy		—	413	—	
$E_{off}$	Turn-off switching energy		—	89	—	
ESR	Gate equivalent series resistance	$f = 1\text{ MHz}, 25\text{ mV}$ , drain short	—	0.69	—	$\Omega$
SCWT	Short circuit withstand time	$V_{DS} = 560\text{V}, V_{GS} = 20\text{V}$	—	3.0	—	$\mu\text{s}$
$E_{AS}$	Avalanche energy, single pulse	$I_D = 40\text{A}$	—	6400	—	$\text{mJ}$

The following table shows the body diode characteristics of this device.  $T_J = 25^\circ\text{C}$  unless otherwise specified. The body diode reverse recovery is characterized, not 100% tested.

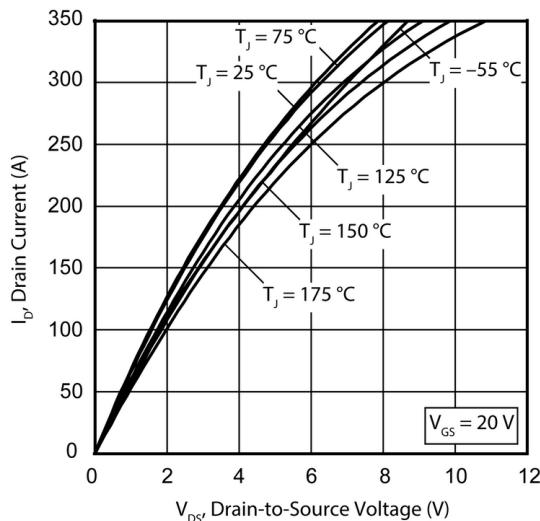
**Table 1-5.** Body Diode Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$V_{SD}$	Diode forward voltage	$I_{SD} = 40\text{A}, V_{GS} = 0\text{V}$	—	3.3	—	V
		$I_{SD} = 40\text{A}, V_{GS} = -5\text{V}$	—	3.6	5.0	
$t_{rr}$	Reverse recovery time	$I_{SD} = 50\text{A}, V_{GS} = -5\text{V}$ , Drive $R_G = 4\Omega$ , $V_{DD} = 470\text{V}$ , $dI/dt = -10900\text{ A}/\mu\text{s}$	—	18	—	ns
$Q_{rr}$	Reverse recovery charge		—	1010	—	
$I_{RRM}$	Reverse recovery current		—	89	—	

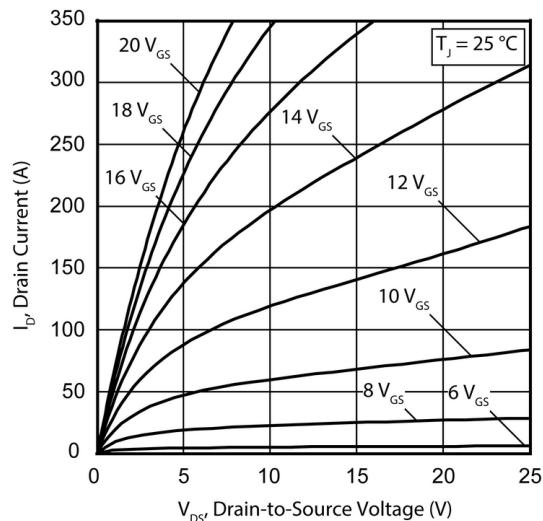
### 1.3 Typical Performance Curves

Data for performance curves are characterized, not 100% tested.

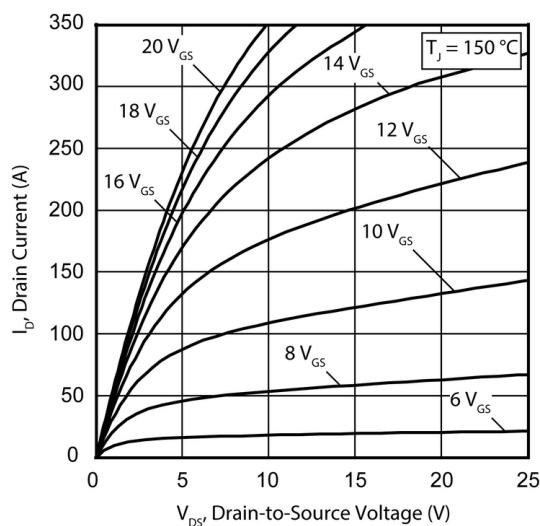
**Figure 1-1.** Drain Current vs.  $V_{DS}$  at  $T_J$



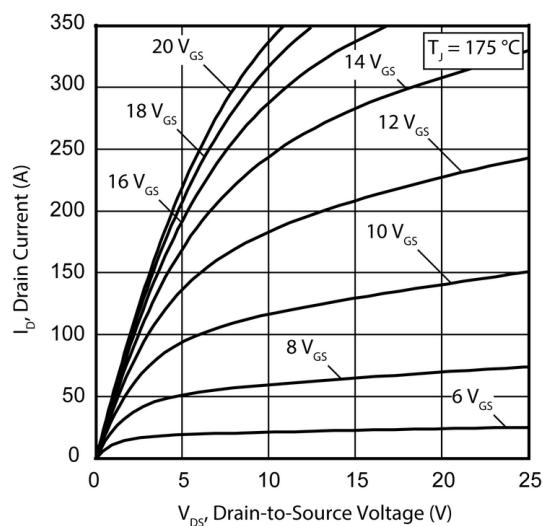
**Figure 1-2.** Drain Current vs.  $V_{DS}$  at  $V_{GS}$



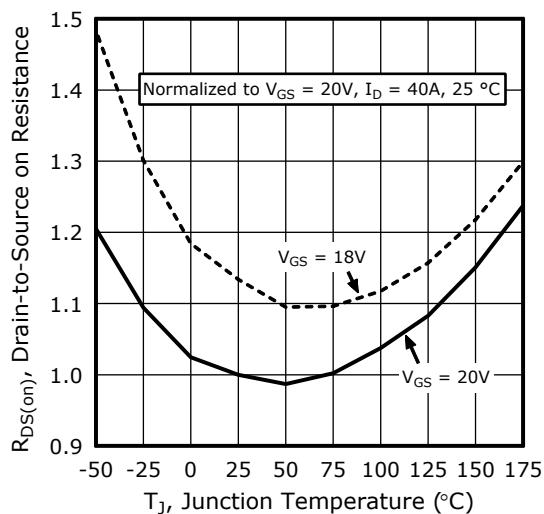
**Figure 1-3.** Drain Current vs.  $V_{DS}$  at  $V_{GS}$



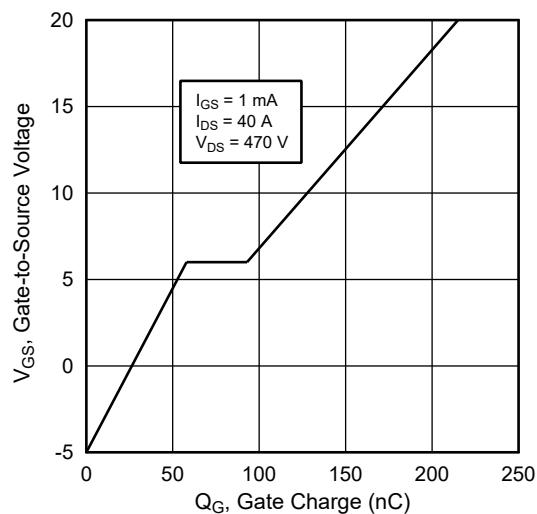
**Figure 1-4.** Drain Current vs.  $V_{DS}$  at  $V_{GS}$



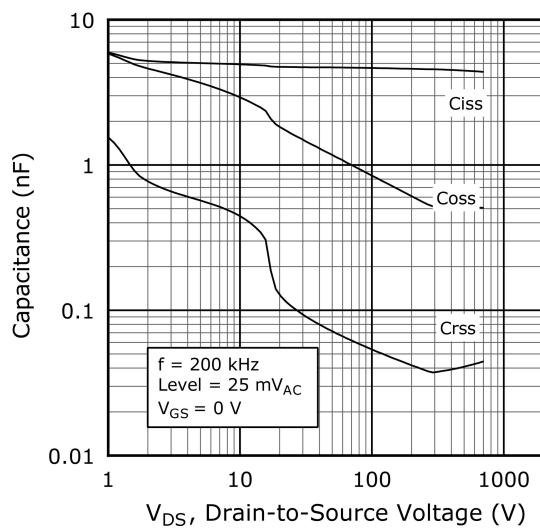
**Figure 1-5.**  $R_{DS(on)}$  vs. Junction Temperature



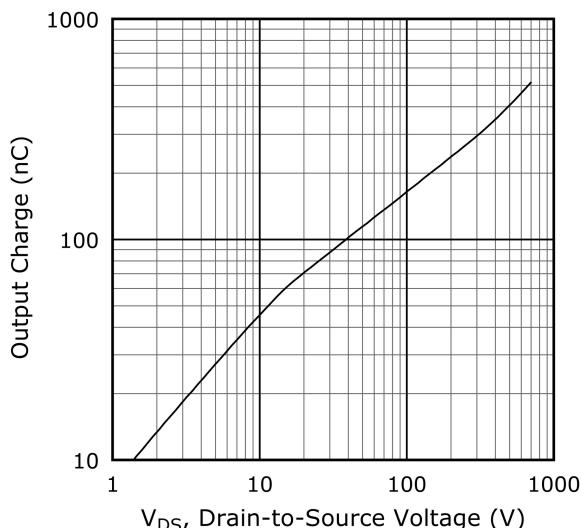
**Figure 1-6.** Gate Charge Characteristics



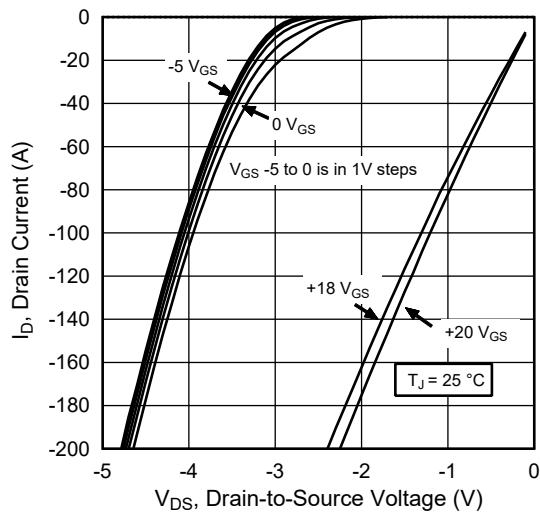
**Figure 1-7.** Capacitance vs. Drain-to-Source Voltage



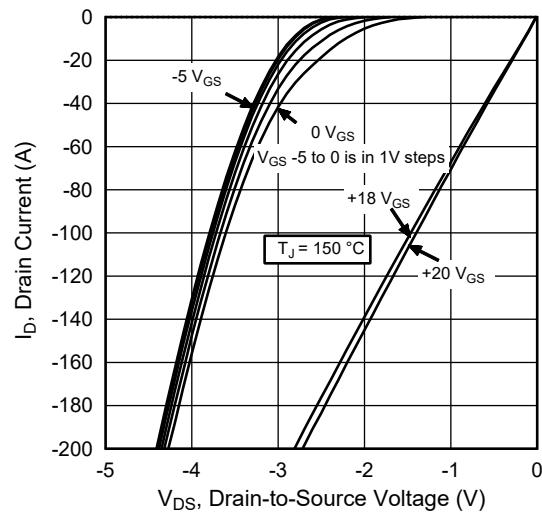
**Figure 1-8.** Output Charge vs. Drain-to-Source Voltage



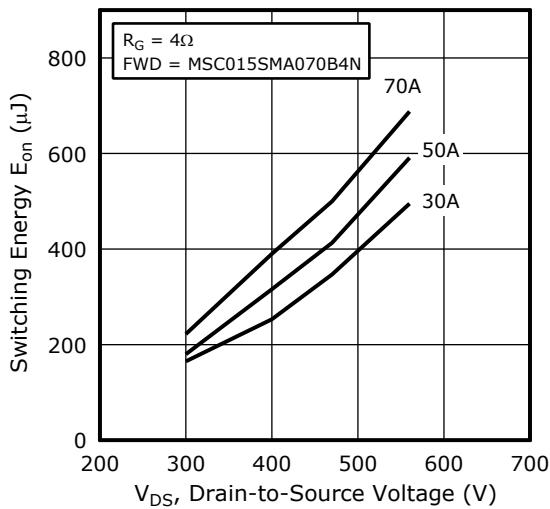
**Figure 1-9.  $I_D$  vs.  $V_{DS}$  3<sup>rd</sup> Quadrant Conduction**



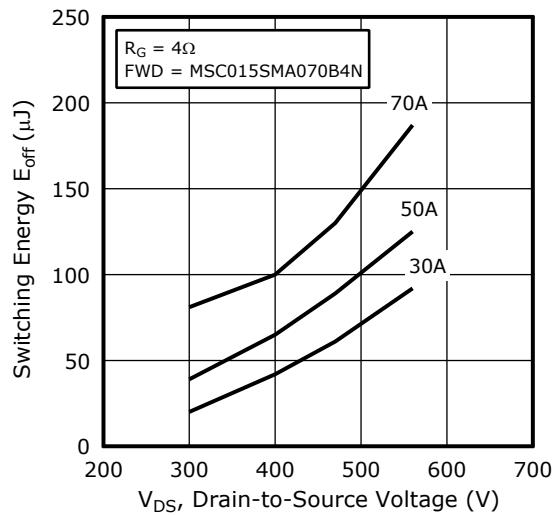
**Figure 1-10.  $I_D$  vs.  $V_{DS}$  3<sup>rd</sup> Quadrant Conduction**



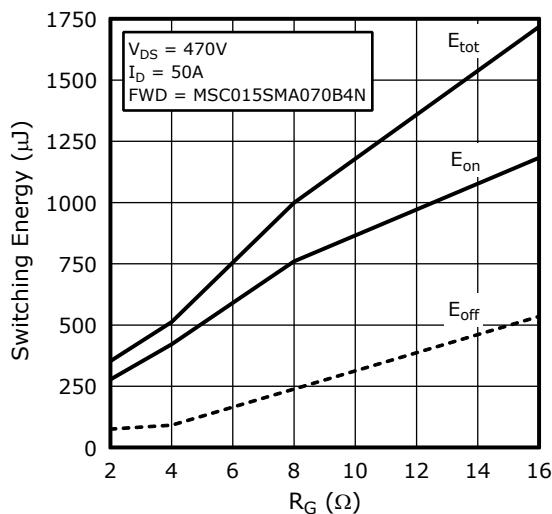
**Figure 1-11. Switching Energy  $E_{on}$  vs.  $V_{DS}$  &  $I_D$**



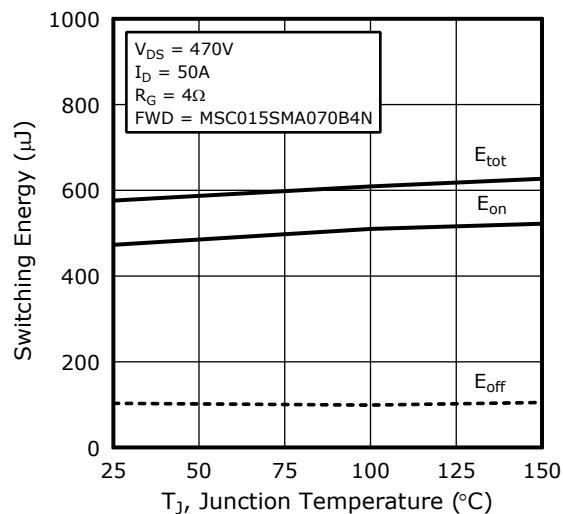
**Figure 1-12. Switching Energy  $E_{off}$  vs.  $V_{DS}$  &  $I_D$**



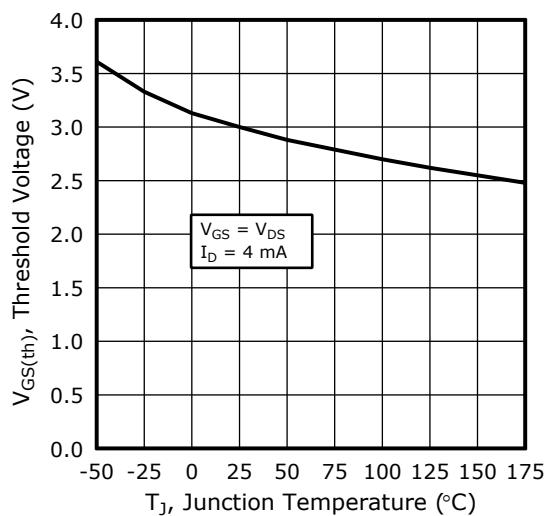
**Figure 1-13.** Switching Energy vs.  $R_G$



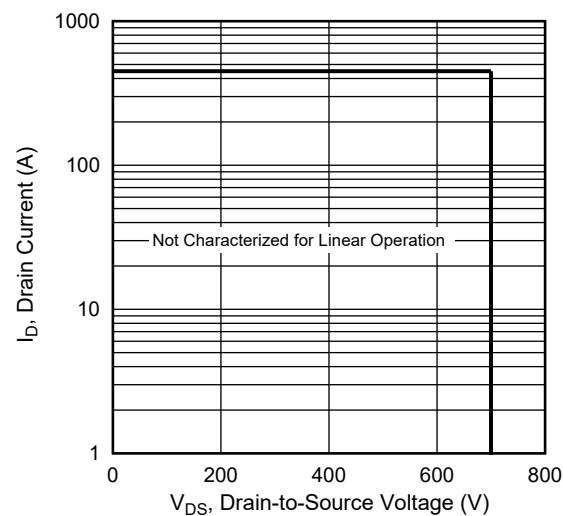
**Figure 1-14.** Switching Energy vs. Junction Temperature



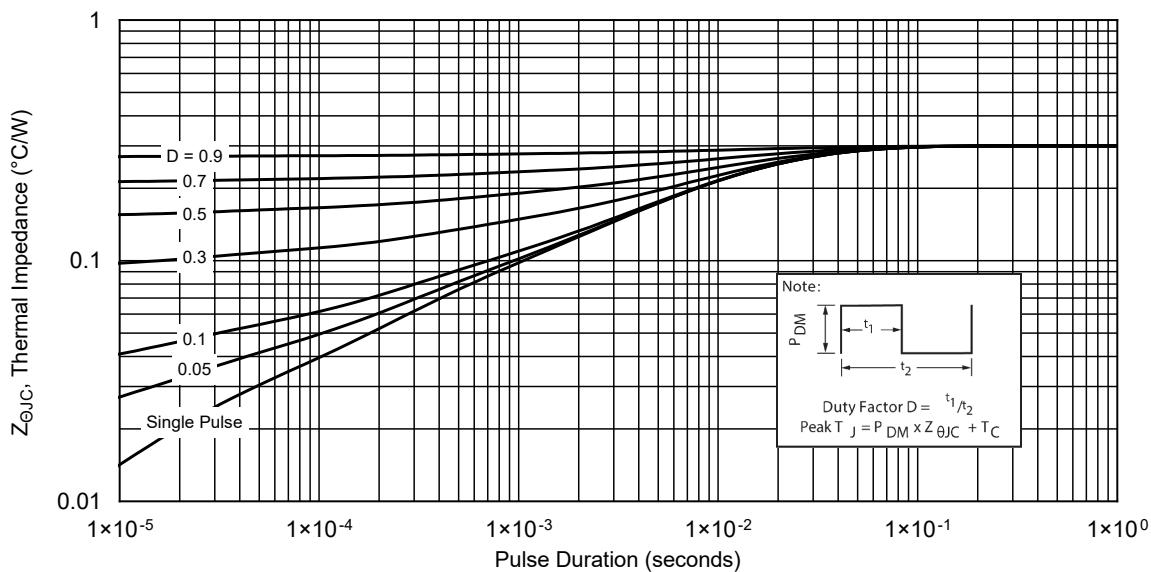
**Figure 1-15.** Threshold Voltage vs. Junction Temperature



**Figure 1-16.** Forward Safe Operating Area

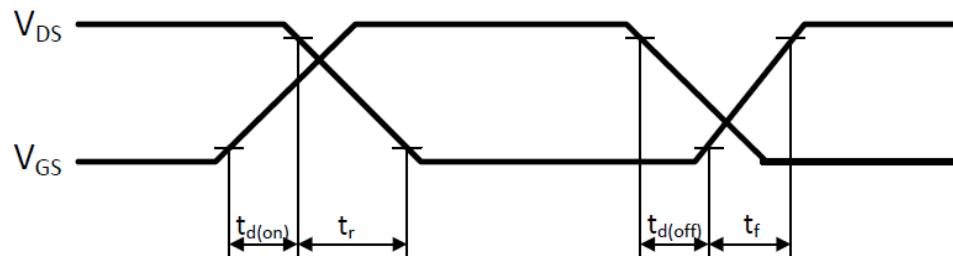


**Figure 1-17.** Maximum Transient Thermal Impedance



The following figure shows the switching waveform diagram of this device.

**Figure 1-18.** Switching Waveform



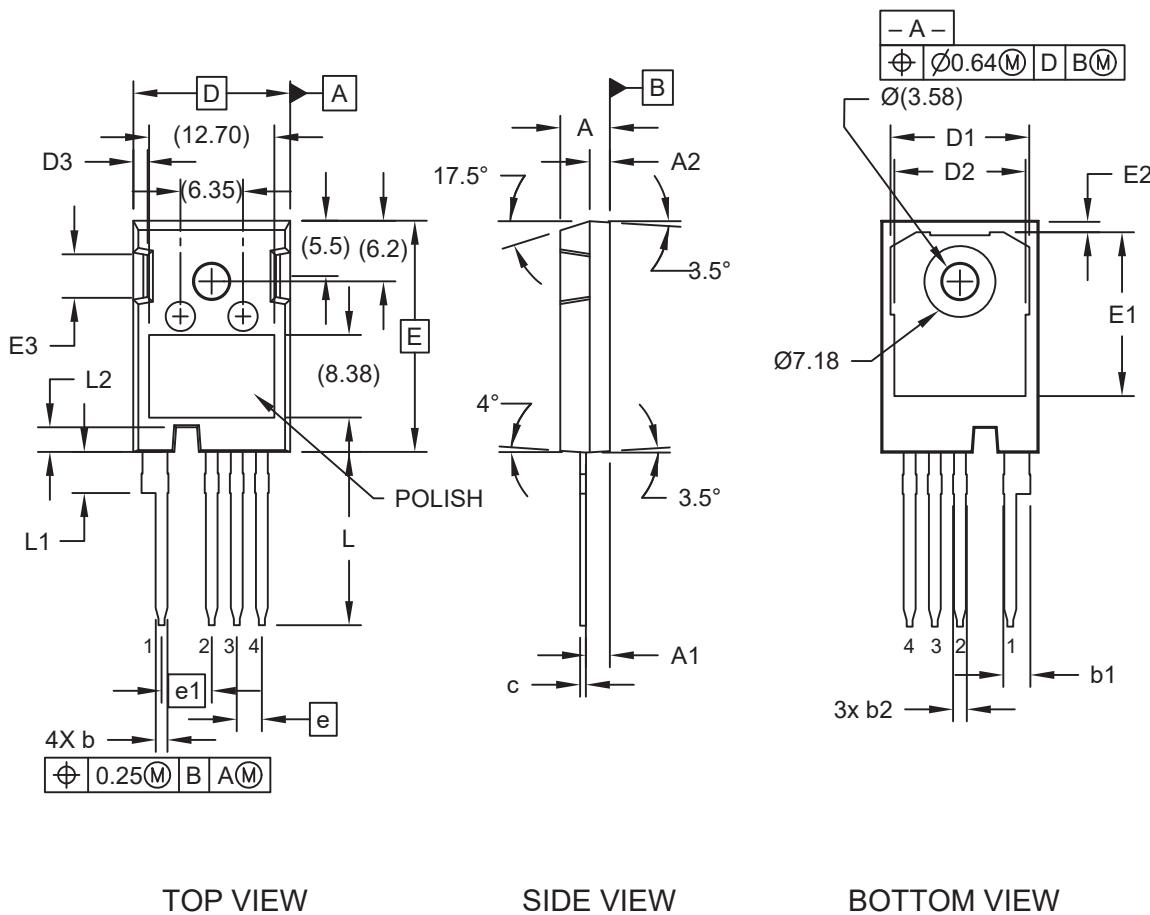
## 2. Package Specification

This section shows the package specification of this device.

## 2.1 Package Outline Drawing

The following figure illustrates the TO-247 notched-4L package outline of this device.

**Figure 2-1.** Package Outline Drawing



The following table shows the TO-247 notched-4L dimensions and should be used in conjunction with the package outline drawing.

**Table 2-1.** TO-247 Notched-4L Dimensions

Symbol	Description	Min. (mm)	Nom. (mm)	Max. (mm)
N	Number of terminals	4		
e	Pitch	2.54 BSC		
		5.08 BSC		
A	Overall height	4.83	5.02	5.21
A1	Standoff	2.29	2.41	2.54
A2	Exposed pad thickness	1.91	2.03	2.16
c	Terminal thickness	0.55	0.60	0.68
D	Overall length	15.75	15.94	16.13

.....continued

Symbol	Description	Min. (mm)	Nom. (mm)	Max. (mm)
D1	Exposed pad length	13.10	13.62	14.15
D2		12.38	12.90	13.43
D3	Cutout length	1.00	1.45	1.90
E	Overall width	23.30	23.45	23.60
E1	Exposed pad width	16.25	16.95	17.65
E2	Exposed pad gap to edge	0.95	1.10	1.25
E3	Cutout width	3.68	4.39	5.10
b	Terminal width	1.07	1.20	1.33
b1	Terminal shoulder width (X1)	2.39	2.66	2.94
b2	Terminal shoulder width (X3)	1.07	1.33	1.60
L	Terminal length	17.31	17.56	17.82
L1	Terminal shoulder length	3.97	4.17	4.37
L2	Notch depth	2.35	2.50	2.65

**Note:**

Dimensioning and tolerancing per ASME Y14.5M.

- BSC: Basic dimension. Theoretically exact value shown without tolerances.

### 3. Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

**Table 3-1.** Revision History

Revision	Date	Description
A	07/2024	Initial revision

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